

LEAD FREE SOLDER PASTE

LH Halogen free type

Compatible with halogen free standards,
while achieving the same level of solderability
as the conventional products.

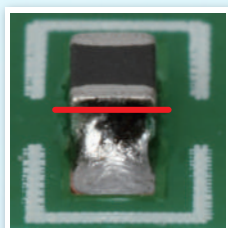
Fine Solder



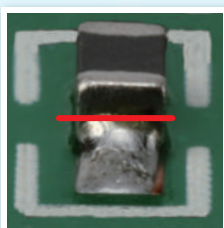
Product Features

Halogen free, with excellent solderability

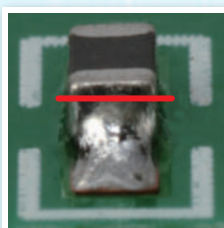
Performing with excellent solderability equivalent to the standard products that are not halogen free, while achieving such high level of reliability as meeting halogen free standards (chlorine(Cl): ≤900 ppm, bromine (Br): ≤900 ppm, Chlorine (Cl) and Bromine (Br): ≤1,500 ppm).



FLF01-LH



Equivalent products from other manufacturers



Standard products

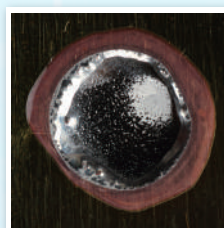
Mount a 2010 chip after printing solder paste onto a printed board with a thickness of 120 μm.

Preheat at 160 to 190°C, reflow heat for 90 sec at 240°C.

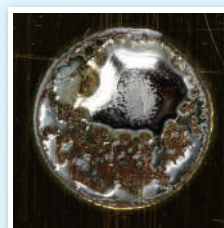
Observe solderability

Excellent heat resistance

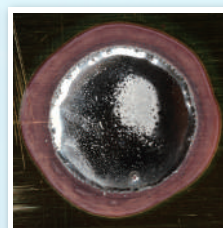
Expanded activation temperature range due to our unique activation agent technology resulted in improved heat resistance.



FLF01-LH



Equivalent products from other manufacturers



Standard products

Print solder paste onto a copper substrate with
φ 6.5 mm and a thickness of 200 μm.

Preheat at 200°C, 3 min

Reflow heat at 240°C

Observe melting conditions

Items	FLF01-LH	Test method
Alloy composition	Sn96.5%-Ag3.0%-Cu0.5%	JIS Z3282
Solidus temperature	Approx. 217°C	JIS Z3282
Liquidus temperature	Approx. 219°C	JIS Z3282
Particle size	20~38μm(Type4)	JIS Z3284(J-STD-005)
Flux content	11.50%	JIS Z3197
Halide content	0.03%	JIS Z3197
Viscosity	190Pa·s	JIS Z3284
Thixotropy index	0.54	JIS Z3284
Copper plate corrosion test	Pass	JIS Z3197
Insulation resistance test (85°C 85%RH 168hr)	> 1.0×10 ⁹ Ω	JIS Z3197
Migration test (85°C 85%RH 1,000hr)	Pass	JIS Z3197
Spread rate	87%	JIS Z3197

